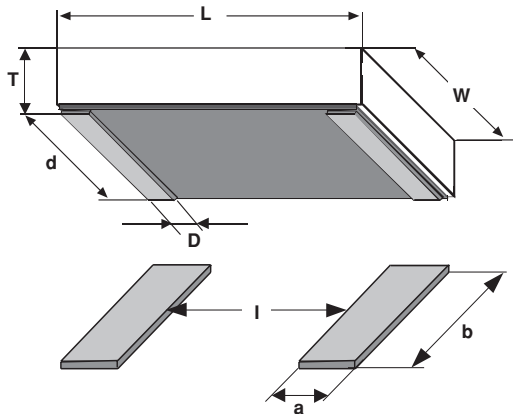
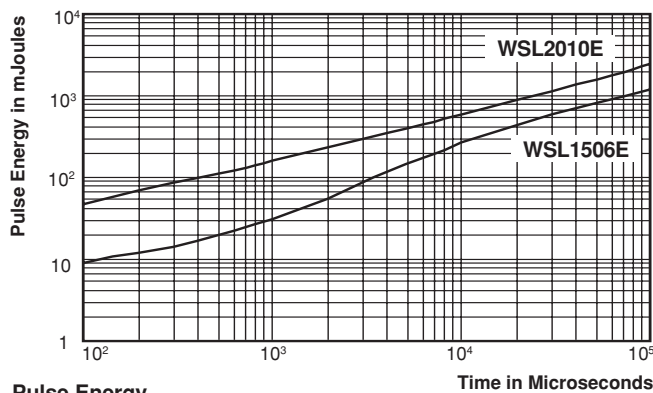




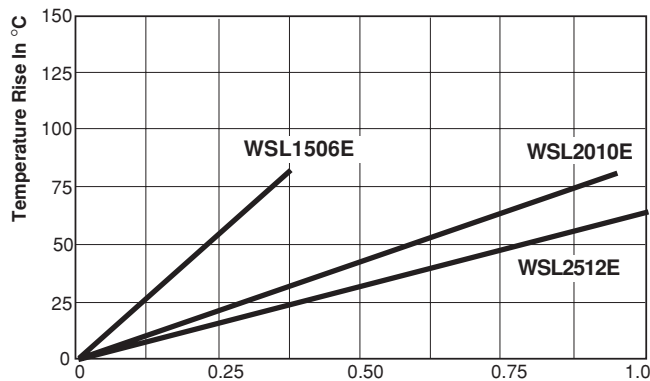
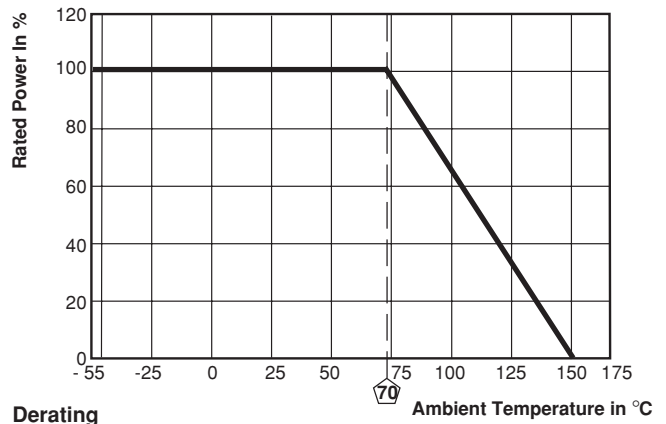
**DIMENSIONS**


SIZE	DIMENSIONS in inches [millimeters]				
INCH	L	W	T <sub>max</sub>	D	d
1506	0.15 ± 0.005 [3.81 ± 0.13]	0.062 ± 0.003 [1.57 ± 0.08]	0.025 [0.64]	0.012 ± 0.003 [0.30 ± 0.08]	0.059 ± 0.003 [1.50 ± 0.08]
2010	0.200 ± 0.005 [5.08 ± 0.13]	0.100 ± 0.003 [2.54 ± 0.08]	0.025 [0.64]	0.020 ± 0.003 [0.51 ± 0.08]	0.097 ± 0.003 [2.46 ± 0.08]
2512	0.250 ± 0.005 [6.35 ± 0.13]	0.126 ± 0.003 [3.20 ± 0.08]	0.025 [0.64]	0.024 ± 0.003 [0.61 ± 0.08]	0.123 ± 0.003 [3.12 ± 0.08]

SIZE	SOLDER PAD RECOMMENDATIONS in inches [millimeters]		
INCH	a	b	l
1506	0.015 [0.38]	0.062 [1.57]	0.118 [3.00]
2010	0.023 [0.58]	0.100 [2.54]	0.153 [3.89]
2512	0.027 [0.69]	0.126 [3.20]	0.196 [4.98]


**Pulse Energy Plot:**

This represents the energy in each of 50 pulses, with a 1 second rest between pulses, that it takes to shift the WSL....E resistance ± (0.50% + 0.01Ω).

**Pulse Energy**

**Temperature Rise**

**Derating**

<b>PERFORMANCE</b>		
TEST	CONDITIONS OF TEST	TEST LIMITS
Thermal Shock	-55°C to +150°C, 100 cycles, 15 minutes at each extreme	±(0.20% + 0.01Ω)
Short Time Overload	5 x rated power for 5 seconds	±(0.20% + 0.01Ω)
Low Temperature Storage	-65°C for 24 hours	±(0.20% + 0.01Ω)
High Temperature Exposure	1000 hours @ +150°C	±(0.50% + 0.01Ω)
Moisture Resistance	MIL-STD-202, Method 106, 0% power, 7a and 7b not required	±(0.50% + 0.01Ω)
Load Life	1000 hours @ rated power, +70°C, 1.5 hours "ON", 0.5 hours "OFF"	±(0.50% + 0.01Ω)
Vibration	MIL-STD-202, Method 204D	±(0.10% + 0.01Ω)
Mechanical Shock	100 G's for 6 milliseconds, 5 pulses	±(0.10% + 0.01Ω)
Resistance to Soldering Heat	+260°C solder, 10-12 seconds dwell, 25mm/second emergence	±(0.50% + 0.01Ω)